

ABSTRACT

A method of mounting conductive balls comprises a step of setting, on a substrate, a mask that includes a plurality of apertures for disposing conductive balls on the substrate and a filling step. The filling step includes using a head that moves along a surface of the mask, holding a group of conductive balls in an area that is part of the surface of the mask, and moving the area so that parts of a path taken by the area overlap. By limiting the area where filling is carried out and moving the conductive balls while gathering the conductive balls in this area, it is possible to prevent losses for the conductive balls, to increase the filling efficiency, and to suppress the number of unfilled apertures.